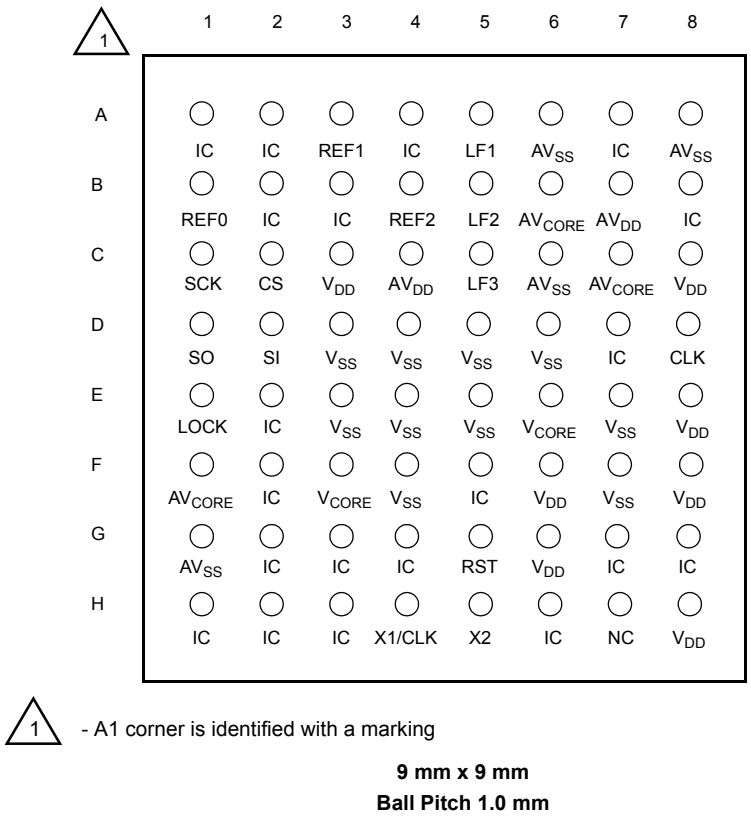


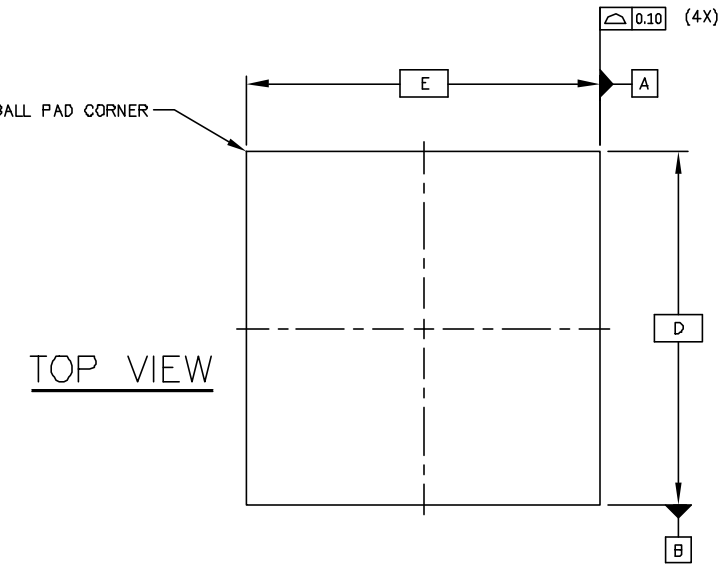
Figure 2 - Pin Connections

Pin Description

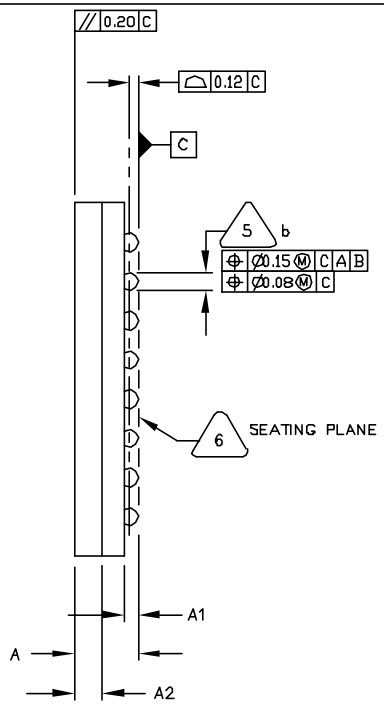
Pin #	Name	I/O Type	Description
B1 A3 B4	REF0 REF1 REF2	I_d	**Reference Inputs (LVCMOS, Schmitt Trigger).** These reference inputs are used for synchronizing the PLL. These pins are internally pulled down to Vss.
D8	CLK	O	**SONET/SDH/Ethernet Clock Output (LVCMOS).** This output clock is configurable as 77.76 MHz, 25 MHz, and 50 MHz. Default is 77.76 MHz.
G5	RST	I	**Reset (LVCMOS, Schmitt Trigger).** A logic low at this input resets the device. To ensure proper operation, the device must be reset after power-up. Reset should be asserted for a minimum of 300 ns.
E1	LOCK	O	**Lock Indicator (LVCMOS).** This is the lock indicator pin for the PLL. This output goes high when the DPLL's output is frequency is phase locked to the input reference.
A5	LF1	A	**External Analog PLL Loop Filter terminal.**
B5	LF2	A	**Analog PLL External Loop Filter Reference.**
C5	LF3	A	**Analog PLL External Loop Filter Reference.**
H4	X1/CLK	I	**Oscillator Master Clock Input (LVCMOS).** This input accepts a 20 MHz reference from a clock oscillator (XO, XTAL). The stability and accuracy of the clock at this input determines the free-run accuracy and the long term holdover stability of the output clocks.
H5	X2	O	**Oscillator Master Clock Output (LVCMOS).** This pin is used for connection with an crystal. This pin must be left unconnected when the X1 pin is connected to a clock oscillator.
C1	SCK	I	**Clock for Serial Interface (LVCMOS).** Serial interface clock.
D2	SI	I	**Serial Interface Input (LVCMOS).** Serial interface data input pin.
D1	SO	O	**Serial Interface Output (LVCMOS).** Serial interface data output pin.
C2	CS	I_u	**Chip Select for Serial Interface (LVCMOS).** Serial interface chip select. This pin is internally pulled up to Vdd.
F5 A1 A2 A4 A7 B8 D7 E2 G7 H1 B2 G4 G2 G3 G8 H3 F2	IC		**Internal Connection.** Leave unconnected.

Pin #	Name	I/O Type	Description
H6 B3 H2	IC		**Internal Connection.** Connect to ground.
H7	NC		**No Connection.** Leave unconnected.
C3 C8 E8 F6 F8 G6 H8	V_{DD}	P P P P P P P	**Positive Supply Voltage.** +3.3 V_{DC} nominal.
E6 F3	V_{CORE}	P P	**Positive Supply Voltage.** +1.8 V_{DC} nominal.
B7 C4	AV_{DD}	P P	**Positive Analog Supply Voltage.** +3.3 V_{DC} nominal.
B6 C7 F1	AV_{CORE}	P P P	**Positive Analog Supply Voltage.** +1.8 V_{DC} nominal.
D3 D4 D5 D6 E3 E4 E5 E7 F4 F7	V_{SS}	G G G G G G G G G G	**Ground.** 0 Volts.
A6 A8 C6 G1	AV_{SS}	G G G G	**Analog Ground.** 0 Volts.

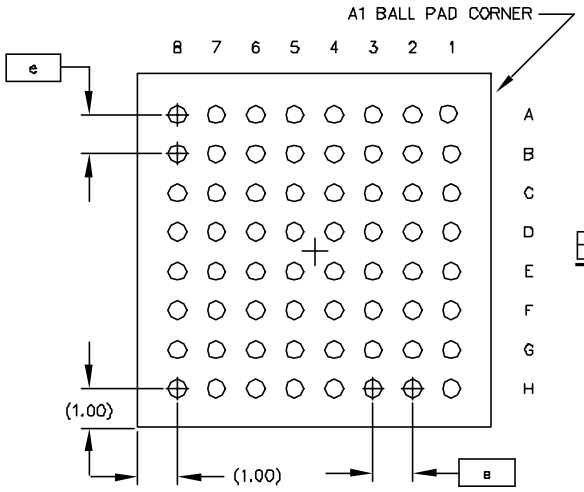
I - Input
I_d - Input, Internally pulled down
I_u - Input, Internally pulled up
O - Output
A - Analog
P - Power
G - Ground



TOP VIEW



SIDE VIEW



BOTTOM VIEW

64 SOLDER BALLS

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.52	1.62	1.72
A1	0.31	0.36	0.41
A2	0.65	0.70	0.75
b		0.46 Typ.	
D		9.00 REF.	
E		9.00 Ref.	
e		1.0 Ref	
n		64	

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 64.

3. Not to Scale.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M–1994.

NOTES: UNLESS OTHERWISE SPECIFIED

	1			
	CDCA			
	15April05			

ZARLINK SEMICONDUCTOR

	Package Code GG
Previous package codes N/A	Package Outline for 64ball 9x9mm, 1.0 mm Pitch, 4 layer, CABGA
	111039

For more information about all Zarlink products visit our Web Site at

www.zarlink.com

TECHNICAL DOCUMENTATION - NOT FOR RESALE